

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): An adhesive label comprising

(1) a circuit substrate;

(2) an entire data carrier element for a contactless data carrier system containing
~~electronic components~~ an IC chip, said data carrier being formed-carried on at least one surface
of said circuit substrate, and said IC chip being carried on only one surface of said circuit
substrate; and

(3) an adhesive layer on said ~~electronic components~~ data carrier element containing said
IC chip,

wherein said circuit substrate, said ~~electronic components~~ data carrier element containing
said IC chip, and said adhesive layer are sequentially laminated, and

said adhesive layer is in direct contact with said ~~electronic components~~ data carrier
element containing said IC chip and is suitable for application to an article, when said adhesive
label is applied to an article, said adhesive layer comes into direct contact with the surface of the
article.

2. (original): The adhesive label according to claim 1, wherein said adhesive layer is a pressure sensitive adhesive layer.

3. (canceled).

4. (currently amended): The adhesive label according to claim 1 or 2, wherein ~~an~~ said entire data carrier element ~~for a contactless data carrier system containing said electronic components~~ IC chip is formed on one side of said circuit substrate, and said adhesive layer is formed on said entire data carrier element.

5. (currently amended): The adhesive label according to claim 1 or 2, wherein a surface layer is provided on a circuit substrate surface that is on the reverse side to a surface carrying said ~~electronic element~~ data carrier element containing said IC chip.

6. (currently amended): The adhesive label according to claim 1, wherein ~~said electronic components~~ antenna coils of said data carrier element are separately formed on each surface of said circuit substrate and connected to each other by a through-hole to integrate both

~~electronic components~~ said antenna coils to form ~~an~~ said entire data carrier element for a said contactless data carrier system, said adhesive layer is formed on one of ~~said separately formed~~ ~~electronic components~~ surface carrying said antenna coils and said IC chip, and a surface layer is formed directly on the other of ~~said separately formed electronic components~~ surface carrying said separately formed antenna coils without said IC chip.

7. (currently amended): The adhesive label according to claim 4, wherein a surface layer is provided on a circuit substrate surface that is on the reverse side to a surface carrying said ~~electronic element~~ data carrier element containing said IC chip.

8. (currently amended): An adhesive label consisting of a circuit substrate, an entire data carrier element for a contactless data carrier system which is formed on one side of said circuit substrate, and an adhesive layer formed on said entire data carrier element, said entire data carrier element having antenna coils and an IC chip.

9. (previously presented): The adhesive label according to claim 8, wherein said adhesive layer is a double-coated adhesive layer.

10. (currently amended): An adhesive label consisting of a circuit substrate, an entire data carrier element for a contactless data carrier system which is formed on one side of said circuit substrate, an adhesive layer formed on said entire data carrier element, and a surface layer provided on the circuit substrate surface that is on the reverse side to a surface carrying said entire data carrier element, said entire data carrier element having antenna coils and an IC chip.

11. (previously presented): The adhesive label according to claim 10, wherein said adhesive layer is a double-coated adhesive layer.

12. (currently amended): An adhesive label consisting of a circuit substrate, an entire data carrier element for a contactless data carrier system, said data carrier element comprising an IC chip carried on one surface of said circuit substrate, and antenna coils ~~which is~~ separately formed on each surface of said circuit substrate and connected to each other by a through-hole to integrate both separately formed parts of said ~~data carrier element~~ antenna coils to form said entire data carrier element, an adhesive layer formed on one ~~of~~ surface carrying said IC chip and said separately formed part of said ~~data carrier element~~ antenna coils, and a surface layer formed directly on the other of said separately formed part of said ~~data carrier element~~ antenna coils without said IC chip.

13. (previously presented): The adhesive label according to claim 12, wherein said adhesive layer is a double-coated adhesive layer.

14. (currently amended): The adhesive label according to claim 12, wherein ~~electronic components are formed only on one surface covered with said adhesive layer~~ covering said data carrier element having said separately formed part of said antenna coils and said IC chip ~~which~~ comes into direct contact with the surface of an article when said adhesive label is applied on said article.

15. (canceled).